

**Amendments to the Claims:**

This listing of claims will replace all prior version, and listings, of claims in the application:

**Listing of Claims:**

1-10. (Canceled).

11. (New) A pressure sensor comprising:

a pressure sensor element having a diaphragm area; and

a first fixing area, a pressure to be measured exerting a force action on the diaphragm area, the first fixing area being connected to a second fixing area of a fixing element to fix the pressure sensor element;

wherein the first fixing area and the second fixing area are pressure-loaded by the force action.

12. (New) The pressure sensor of claim 11, wherein the pressure sensor element is at least one of made of a semiconductor material and is manufactured using bulk micromechanics.

13. (New) The pressure sensor of claim 11, wherein the pressure sensor handles high pressures, including pressures up to approximately 1,000 bar.

14. (New) The pressure sensor of claim 11, wherein the pressure sensor handles pressures exceeding 1,000 bar.

15. (New) The pressure sensor of claim 11, wherein the fixing element, with respect to its coefficient of thermal expansion, is adapted to the sensor element.

16. (New) The pressure sensor of claim 11, wherein a connecting material is between the first fixing area and the second fixing area, the connecting material being comparatively soft.

17. (New) The pressure sensor of claim 11, wherein resistor elements are provided in the diaphragm area.

18. (New) The pressure sensor of claim 11, wherein a connecting surface between the first fixing area and the second fixing area is parallel to a diaphragm plane.

19. (New) The pressure sensor of claim 11, wherein a connecting surface between the first fixing area and the second fixing area is at an acute angle to a diaphragm plane.
20. (New) The pressure sensor of claim 11, wherein a cross section of the fixing element tapers in a direction of the second fixing area.